

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KENZO IMAI	02/21/2020
KOJI SAWANOBORI	02/21/2020
NOBUAKI WATANABE	02/25/2020
DAISUKE YAGINUMA	02/21/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	NIDEC COPAL CORPORATION
<b>Street Address:</b>	2-18-10 SHIMURA, ITABASHI-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	174-8550
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16803916
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<b>NAME OF SUBMITTER:</b>	BENJAMIN J. HAUPTMAN
<b>SIGNATURE:</b>	/Benjamin J. Hauptman/
<b>DATE SIGNED:</b>	02/27/2020
<b>Total Attachments: 1</b>	
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## ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- |                     |                     |
|---------------------|---------------------|
| 1) Kenzo IMAI       | 2) Koji SAWANOBORI  |
| 3) Nobuaki WATANABE | 4) Daisuke YAGINUMA |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto Nidec Copal Corporation, having a place of business at 2-18-10 Shimura, Itabashi-ku, Tokyo, 174-8550, Japan, its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled:

### CAMERA MODULE SHIELDING MECHANISM AND ELECTRONIC DEVICE

- (a) for which an application for United States Letters Patent was filed on \_\_\_\_\_, and identified by United States Patent Application No. \_\_\_\_\_; or
- (b) for which an application for United States Letters Patent was executed on \_\_\_\_\_.

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Kenzo Imai  
Name: Kenzo IMAI

Feb. 21, 2020  
Date

2) Koji Sawanobori  
Name: Koji SAWANOBORI

Feb. 21, 2020  
Date

3) Nobuaki Watanabe  
Name: Nobuaki WATANABE

Feb. 25, 2020  
Date

4) Daisuke Yaginuma  
Name: Daisuke YAGINUMA

Feb. 21, 2020  
Date